

10/726,755**Patent**
IBM Docket No. FIS920010385US2In the specification:

On page 1, line 1, replace the Title of the Invention with the following:

METHOD OF FORMING A MULTICHIP MODULE HAVING CHIPS ON TWO SIDES

On page 1, after the Title of the Invention, insert the following:

This is a Division of Application No. 10/260,086, filed on September 27, 2002, now US Patent 6,765,152.

On page 19, replace the Abstract of the Disclosure with the following:

A method of forming a multichip module in which a thin film structure is formed on a temporary carrier and then an electrically insulating frame is attached to the thin film structure. A semiconductor device is attached to the thin film structure and then the temporary carrier is removed. Lastly, at least one semiconductor device is attached to the other side of the thin film structure. There is interconnectivity through the thin film structure between the semiconductor devices and the frame.